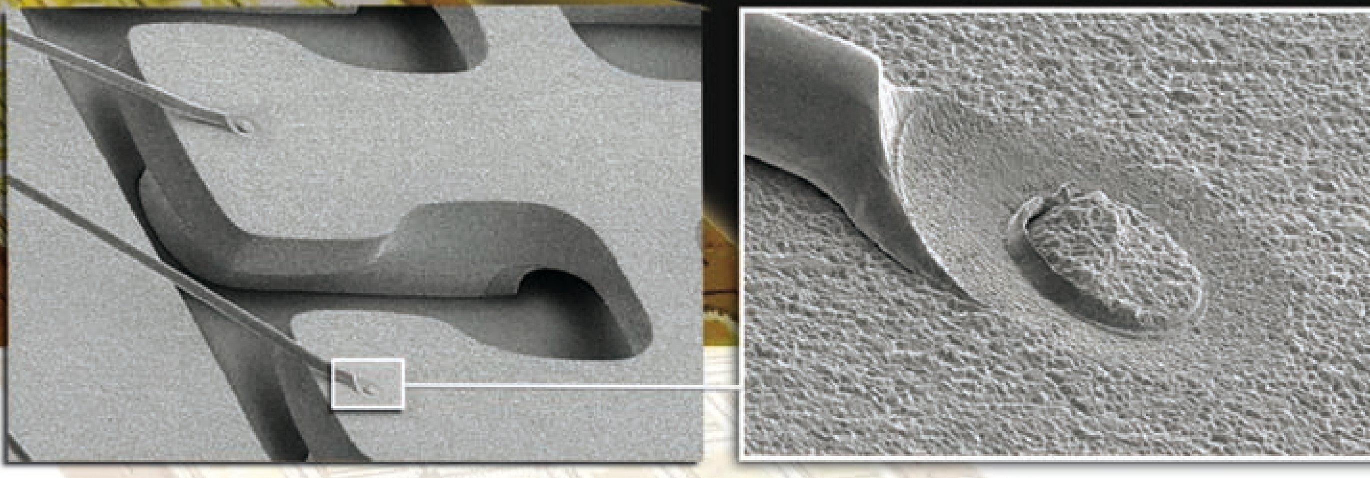
QFN PACKAGE GOLD & COPPER WIRE BONDING CAPILLARY



SQ The Solution

SPT
small precision tools

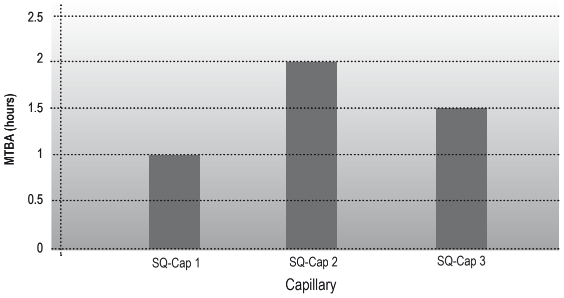
HIGHER PRODUCTIVITY & RELIABILITY

IMPROVED MTBA

With SQ capillary, there will be lesser assist due to short tail or broken stitch which is inherent with bonding QFN package. Experience more machine uptime!

SQ Capillary MTBA Performance using different CU wire diameter

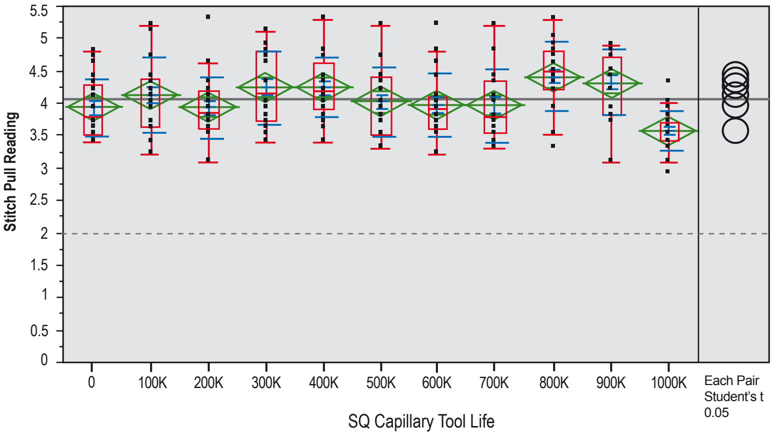
Capillary Part Number	SQ - Cap 1	SQ - Cap 2	SQ - Cap 3
Wire Size	24µm (Cu)	29µm (Cu)	33µm (Cu)
Package	QFN-Tapeless	QFN-Tapeless	QFN-Tapeless
Leadframe Plating Type	NiPdAu	NiPdAu	NiPdAu
BPO	75µm	80µm	85µm
BPP	102µm	94µm	98µm



HIGHER CAPILLARY TOUCHDOWN

SQ capillary coupled with optimized bonding parameters, has proven to deliver an increase in the capillary tool life as lower bond force (BF) is utilized to bond the QFN package.

Oneway Analysis of Stitch Pull Reading By SQ Capillary Tool Life



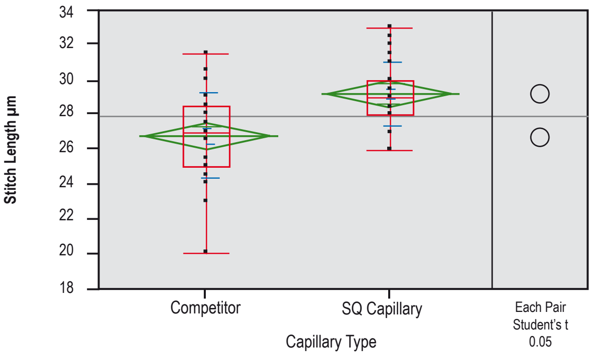
Application Detail

Capillary : **SQ-25075-355F08-ZU39TS-Y**
Wire : 20µm Au wire
Package : QFN without tape with Ag plating
BPP : 55µm
Stitch Pull Reading : 2gms (minimum)

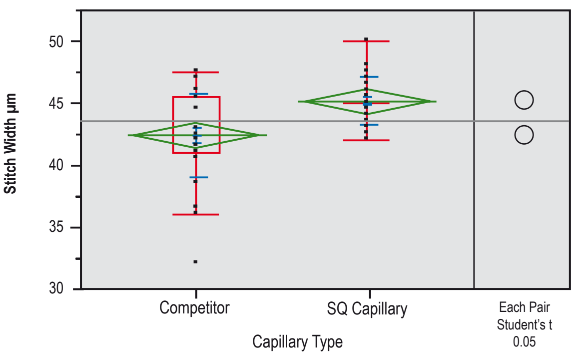
PROVEN RELIABILITY

Whether on gold or copper wire, the SQ capillary is designed to enhance the formation of larger & width stitch bond that will effectively increase the stitch pull reading values & longer size copper remains.

Oneway Analysis of Stitch Length by Capillary Type



Oneway Analysis of Stitch Width by Capillary Type



COMPETITOR

SQ CAPILLARY